

RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 7.0 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1621	A7	MAR '00	25224	9950 OSEP	DE940040AAC	SOIC	50	50	0
DS1869	A3	JUN '00	25547	0017 CPS (ChipPac, China)	DH833210AAB	SOIC	25	48	0

RELIABILITY MONITOR

STRESS: VAPOR PHASE REFLOW

CONDITIONS: 217C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2181A	A2	JUL '00	25816	0016	OSEP	DE004552ABD	PLCC	3	241	0
DS5002	C5	JUL '00	25824	0027	ATK (Anam, K)	DN012259AAL	MQFP	3	203	0
DS5002	C5	JAN '01	26506	0047	ATK (Anam, K)	DN028766AAD	MQFP	3	203	0
DS87C520	A15	AUG '00	25864	0027	OSEP	DE013425AAD	PLCC	3	239	0
DS87C520	A15	NOV '00	26198	0042	OSEP	DE029195AAB	PLCC	3	236	0

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1232	C2-L	OCT '00	26086	0039	OSEP	DE028679ADB	SOIC	4	0
DS1267	A2	FEB '00	25172	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	4	0
DS1267	A1	AUG '00	25831	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	4	0
DS1621	A7	MAR '00	25217	9950	OSEP	DE940040AAC	SOIC	4	0
DS1803	A2	NOV '99	24735	9923	ATP (Anam, PI)	DK913631AAA	SOIC	4	0
DS1803	A2	FEB '00	25188	0007	OSEP	DE946274AAA	SOIC	4	0
DS1803	A2	MAY '00	25435	0013	OSEP	DE951193AAF	SOIC	4	0
DS1803	A2	AUG '00	25922	0034	OSEP	DE023435AAB	SOIC	4	0
DS1869	A3	JUN '00	25540	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	4	0
DS2108	B7	MAY '00	25522	0019	ATP (Anam, PI)	DK007198AAF	SOIC	4	0
DS2108	B7	AUG '00	25854	0029	ATP (Anam, PI)	DK016058AA	SOIC	4	0
DS2118M	B1	SEP '00	25940	0033	ATK (Anam, K)	DN020718AAD	SSOP	4	0
DS21352	A4	DEC '00	26352	0044	ATP (Anam, PI)	DK031452AB	LQFP	4	0
DS2154	A2	SEP '00	25955	0034	ATP (Anam, PI)	DK022283AAA	LQFP	4	0
DS2154	A2	DEC '00	26374	0036	Stats	DC022275AAB	LQFP	4	0
DS2181A	A2	JUL '00	25815	0016	OSEP	DE004552ABD	PLCC	4	0
DS21Q43	A3-A	JUN '00	25501	0014	ATK (Anam, K)	DN004571AAB	LQFP	4	0
DS21Q43	A3-A	SEP '00	25947	0031	Stats	DC022318AAD	LQFP	4	0
DS21Q43	A3-A	DEC '00	26366	0034	ATK (Anam, K)	DN027568AAC	LQFP	4	0
DS21S07	C1-	FEB '01	26584	0047	Carsem S	DM035532AF	TSSOP	4	0
DS2502	C3	JUN '00	25565	0011	Carsem S	DM941230AG	SOIC	4	0
DS2502	C3	JUL '00	25810	0017	CPS (ChipPac, China)	DH948636AG	TSOC	4	0

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT QTY FAIL
DS5002	C5	JUL '00	25823	0027 ATK (Anam, K)	DN012259AAL	MQFP	4 0
DS5002	C5	OCT '00	26056	0033 ATK (Anam, K)	DN022328AAJ	MQFP	4 0
DS5002	C5	JAN '01	26505	0047 ATK (Anam, K)	DN028766AAD	MQFP	4 0
DS87C520	A15	AUG '00	25863	0027 OSEP	DE013425AAD	PLCC	4 0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -40 TO 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1644	B2	& DS9034	26194	0041	Fastech	122179	Power Cap	300	77	0
DS2250	E-T	JUN '00	25681	0026	Dallas	117825	SipStick w/Confor	100	11	0
DS2250	E-T	JUN '00	25681	0026	Dallas	117825	SipStick w/Confor	500	11	0
DS2250	E-T	SEP '00	25963	0035	Fastech	117888	SipStick w/Confor	100	11	0
DS2250	E-T	SEP '00	25963	0035	Fastech	117888	SipStick w/Confor	500	11	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1000	E3	OCT '00	26048	0033	OSEP	DE009456ACE	SOIC	300	40	0
DS1000	E3	OCT '00	26048	0033	OSEP	DE009456ACE	SOIC	1000	37	0
DS1232	C2-L	OCT '00	26091	0039	OSEP	DE028679ADB	SOIC	300	40	0
DS1232	C2-L	OCT '00	26091	0039	OSEP	DE028679ADB	SOIC	1000	40	0
DS1233	A5	JUL '00	25802	0025	Carsem	DM009468AA	SOT223	700	37	0
DS1233	A5	JUL '00	25802	0025	Carsem	DM009468AA	SOT223	1000	36	2
DS1233	A5	OCT '00	26128	0038	Fastech	DA017172ABA	SOT223	700	40	1
DS1233	A5	OCT '00	26128	0038	Fastech	DA017172ABA	SOT223	1000	39	6
DS1233	A5	JAN '01	26445	0049	Fastech	DA033011ABA	SOT223	700	40	0
DS1267	A2	FEB '00	25177	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	300	36	0
DS1267	A2	FEB '00	25177	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	1000	36	0
DS1267	A1	AUG '00	25836	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	300	35	0
DS1267	A1	AUG '00	25836	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	1000	35	0
DS1302	A3	DEC '00	26334	0032	CPS (ChipPac, China)	DH028629AB	PDIP	300	40	0
DS1302	A3	AUG '00	25933	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	300	40	0
DS1302	A3	AUG '00	25933	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	1000	40	0
DS1621	A7	MAR '00	25222	9950	OSEP	DE940040AAC	SOIC	300	40	0
DS1621	A7	MAR '00	25222	9950	OSEP	DE940040AAC	SOIC	1000	40	0
DS1803	A2	NOV '99	24740	9923	ATP (Anam, PI)	DK913631AAA	SOIC	300	40	0
DS1803	A2	NOV '99	24740	9923	ATP (Anam, PI)	DK913631AAA	SOIC	1000	40	0
DS1803	A2	FEB '00	25193	0007	OSEP	DE946274AAA	SOIC	300	35	0
DS1803	A2	MAY '00	25440	0013	OSEP	DE951193AAF	SOIC	300	35	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1803	A2	MAY '00	25440	0013	OSEP	DE951193AAF	SOIC	1000	20	0
DS1803	A2	AUG '00	25927	0034	OSEP	DE023435AAB	SOIC	300	35	0
DS1869	A3	JUN '00	25545	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	300	40	0
DS2108	B7	MAY '00	25527	0019	ATP (Anam, PI)	DK007198AAF	SOIC	300	40	0
DS2108	B7	MAY '00	25527	0019	ATP (Anam, PI)	DK007198AAF	SOIC	1000	40	0
DS2108	B7	AUG '00	25859	0029	ATP (Anam, PI)	DK016058AA	SOIC	300	40	0
DS2108	B7	AUG '00	25859	0029	ATP (Anam, PI)	DK016058AA	SOIC	1000	40	0
DS2108	B7	FEB '01	26581	0051	ATK (Anam, K)	DN041061AAE	SOIC	300	40	0
DS2118M	B1	SEP '00	25945	0033	ATK (Anam, K)	DN020718AAD	SSOP	300	77	0
DS2118M	B1	SEP '00	25945	0033	ATK (Anam, K)	DN020718AAD	SSOP	1000	77	0
DS2118M	B1	DEC '00	26364	0047	ATK (Anam, K)	DN033148ACE	SSOP	300	70	0
DS2118M	B1	DEC '00	26364	0047	ATK (Anam, K)	DN033148ACE	SSOP	1000	70	0
DS21352	A4	DEC '00	26357	0044	ATP (Anam, PI)	DK031452AB	LQFP	300	77	0
DS2154	A2	SEP '00	25960	0034	ATP (Anam, PI)	DK022283AAA	LQFP	300	63	0
DS2154	A2	SEP '00	25960	0034	ATP (Anam, PI)	DK022283AAA	LQFP	1000	63	0
DS2154	A2	DEC '00	26379	0036	Stats	DC022275AAB	LQFP	300	70	0
DS2154	A2	DEC '00	26379	0036	Stats	DC022275AAB	LQFP	1000	70	0
DS2175	D1	OCT '00	26110	0042	ATP (Anam, PI)	DK031506AAC	SOIC	300	40	0
DS2181A	A2	JUL '00	25820	0016	OSEP	DE004552ABD	PLCC	300	60	0
DS21Q43	A3-A	JUN '00	25506	0014	ATK (Anam, K)	DN004571AAB	LQFP	300	70	0
DS21Q43	A3-A	JUN '00	25506	0014	ATK (Anam, K)	DN004571AAB	LQFP	1000	69	0
DS21Q43	A3-A	SEP '00	25952	0031	Stats	DC022318AAD	LQFP	300	70	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS21Q43	A3-A	SEP '00	25952	0031	Stats	DC022318AAD	LQFP	1000	70	0
DS2401	C2	DEC '00	26339	0035	Fastech	DM014457AD	TO92	300	40	0
DS2401	C2	DEC '00	26339	0035	Fastech	DM014457AD	TO92	1000	39	0
DS2502	C3	JUN '00	25570	0011	Carsem S	DM941230AG	SOIC	300	34	0
DS2502	C3	JUN '00	25570	0011	Carsem S	DM941230AG	SOIC	1000	34	0
DS2502	C3	JUL '00	25813	0017	CPS (ChipPac, China)	DH948636AG	TSOC	300	72	0
DS2502	C3	JUL '00	25813	0017	CPS (ChipPac, China)	DH948636AG	TSOC	1000	72	0
DS5002	C5	JUL '00	25828	0027	ATK (Anam, K)	DN012259AAL	MQFP	300	37	0
DS5002	C5	JUL '00	25828	0027	ATK (Anam, K)	DN012259AAL	MQFP	1000	37	0
DS5002	C5	OCT '00	26061	0033	ATK (Anam, K)	DN022328AAJ	MQFP	300	38	0
DS5002	C5	OCT '00	26061	0033	ATK (Anam, K)	DN022328AAJ	MQFP	1000	38	0
DS80C320	C5	OCT '00	26066	0038	CPS (ChipPac, China)	DH026369ABA	PDIP	300	40	0
DS80C320	C5	OCT '00	26066	0038	CPS (ChipPac, China)	DH026369ABA	PDIP	1000	40	0
DS80C320	C5	JAN '01	26457	0049	CPS (ChipPac, China)	DH031585BAA	PDIP	300	40	0
DS87C520	A15	AUG '00	25868	0027	OSEP	DE013425AAD	PLCC	300	50	0
DS87C520	A15	AUG '00	25868	0027	OSEP	DE013425AAD	PLCC	1000	50	0
DS87C520	A15	NOV '00	26202	0042	OSEP	DE029195AAB	PLCC	300	45	0
DS87C520	A15	NOV '00	26202	0042	OSEP	DE029195AAB	PLCC	1000	45	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230	B1-	JUL '00	25778	0019	Fastech	117143	Module w/SMT	300	100	1
DS1230	B1-	JUL '00	25778	0019	Fastech	117143	Module w/SMT	1000	99	0
DS1230	B1-Y	JUL '00	25782	0020	Fastech	11387	Low Profile Module	300	77	0
DS1230	B1-Y	JUL '00	25782	0020	Fastech	11387	Low Profile Module	1000	76	0
DS1230	A1-Y	OCT '00	26097	0039	Fastech	120544	Module w/SMT	300	100	0
DS1230	A1-Y	JAN '01	26430	0045	Fastech	305435	Module w/SMT	300	100	0
DS12887	A2-	JUL '00	25808	0027	Fastech	300063	Module w/Bent Fra	300	100	0
DS12887	A2-	JUL '00	25808	0027	Fastech	300063	Module w/Bent Fra	1000	100	0
DS12887	A2-	OCT '00	26072	0040	Fastech	300402	Module w/Bent Fra	300	100	0
DS12887	A2-	OCT '00	26072	0040	Fastech	300402	Module w/Bent Fra	1000	100	0
DS1643	C1	AUG '00	25920	0033	Fastech	121538	Module w/Hi Densit	300	77	0
DS1643	C1	AUG '00	25920	0033	Fastech	121538	Module w/Hi Densit	1000	77	1
DS1643	C1	NOV '00	26181	0042	Fastech	122271	Module w/Hi Densit	300	77	0
DS1991	F1	SEP '00	25938	0036	Dallas	DS922809AA-	Puk Can F50 Rev B	300	77	0
DS1991	F1	SEP '00	25938	0036	Dallas	DS922809AA-	Puk Can F50 Rev B	1000	77	0
DS3816	A-C	& DS3801	26054	0041	Dallas	120701	BGA Module	300	33	5

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 150C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1621	A7	MAR '00	25225	9950 OSEP	DE940040AAC	SOIC	336	50	0
DS1621	A7	MAR '00	25225	9950 OSEP	DE940040AAC	SOIC	1000	50	0
DS2502	C3	JUN '00	25572	0011 Carsem S	DM941230AG	SOIC	336	34	0
DS2502	C3	JUN '00	25572	0011 Carsem S	DM941230AG	SOIC	1000	34	0
DS87C520	A15	AUG '00	25870	0027 OSEP	DE013425AAD	PLCC	336	50	0
DS87C520	A15	AUG '00	25870	0027 OSEP	DE013425AAD	PLCC	1000	50	0
DS87C520	A15	NOV '00	26204	0042 OSEP	DE029195AAB	PLCC	336	48	0
DS87C520	A15	NOV '00	26204	0042 OSEP	DE029195AAB	PLCC	1000	48	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 70C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230	B1-Y	JUL '00	25781	0020	Fastech	11387	Low Profile Module	336	77	0
DS1230	B1-Y	JUL '00	25781	0020	Fastech	11387	Low Profile Module	1000	77	0
DS1643	C1	AUG '00	25919	0033	Fastech	121538	Module w/Hi Densit	336	77	0
DS1643	C1	AUG '00	25919	0033	Fastech	121538	Module w/Hi Densit	1000	77	0
DS1643	C1	NOV '00	26180	0042	Fastech	122271	Module w/Hi Densit	336	77	0
DS1643	C1	NOV '00	26180	0042	Fastech	122271	Module w/Hi Densit	1000	77	0
DS1643	C1	FEB '01	26565	0104	Fastech	301297	Module w/Hi Densit	336	77	0
DS1644	B2	& DS9034	26193	0041	Fastech	122179	Power Cap	336	74	0
DS1991	F1	SEP '00	25937	0036	Dallas	DS922809AA-	Puk Can F50 Rev B	336	77	0
DS1991	F1	SEP '00	25937	0036	Dallas	DS922809AA-	Puk Can F50 Rev B	1000	77	1
DS1992	E5	DEC '00	26343	0046	Dallas	DS028764AA	Tch Can F50	336	77	0
DS1992	E5	DEC '00	26343	0046	Dallas	DS028764AA	Tch Can F50	1000	77	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	B1-	JUL '00	25777	0019 Fastech	117143	Module w/SMT	48	200	0
DS1230	A1-Y	OCT '00	26096	0039 Fastech	120544	Module w/SMT	48	200	0
DS1230	A1-Y	JAN '01	26429	0045 Fastech	305435	Module w/SMT	48	200	0
DS2250	E-T	JUN '00	25680	0026 Dallas	117825	SipStick w/Confor	336	11	0
DS2250	E-T	JUN '00	25680	0026 Dallas	117825	SipStick w/Confor	1000	11	0
DS2250	E-T	SEP '00	25962	0035 Fastech	117888	SipStick w/Confor	336	11	0
DS2250	E-T	SEP '00	25962	0035 Fastech	117888	SipStick w/Confor	1000	11	0
DS3816	A-C	& DS3801	26053	0041 Dallas	120701	BGA Module	336	33	0

RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: MIL-STD-883-2003

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	B1-	JUL '00	25775	0019	Fastech	117143	Module w/SMT		3	2
DS1230	A1-Y	OCT '00	26094	0039	Fastech	120544	Module w/SMT		3	0
DS1230	A1-Y	JAN '01	26427	0045	Fastech	305435	Module w/SMT		3	0
DS12887	A2-	JUL '00	25805	0027	Fastech	300063	Module w/Bent Fra		3	0
DS12887	A2-	OCT '00	26069	0040	Fastech	300402	Module w/Bent Fra		3	0
DS1643	C1	AUG '00	25917	0033	Fastech	121538	Module w/Hi Densit		3	0
DS1643	C1	NOV '00	26178	0042	Fastech	122271	Module w/Hi Densit		3	0
DS1643	C1	FEB '01	26563	0104	Fastech	301297	Module w/Hi Densit		3	0

RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1232	C2-L	OCT '00	26088	0039	OSEP	DE028679ADB	SOIC	4	0
DS1267	A2	FEB '00	25174	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	4	0
DS1267	A1	AUG '00	25833	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	4	0
DS1621	A7	MAR '00	25219	9950	OSEP	DE940040AAC	SOIC	4	0
DS1803	A2	NOV '99	24737	9923	ATP (Anam, PI)	DK913631AAA	SOIC	4	0
DS1803	A2	FEB '00	25190	0007	OSEP	DE946274AAA	SOIC	4	0
DS1803	A2	MAY '00	25437	0013	OSEP	DE951193AAF	SOIC	4	0
DS1803	A2	AUG '00	25924	0034	OSEP	DE023435AAB	SOIC	4	0
DS1869	A3	JUN '00	25542	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	4	0
DS2108	B7	MAY '00	25524	0019	ATP (Anam, PI)	DK007198AAF	SOIC	4	0
DS2108	B7	AUG '00	25856	0029	ATP (Anam, PI)	DK016058AA	SOIC	4	0
DS2118M	B1	SEP '00	25942	0033	ATK (Anam, K)	DN020718AAD	SSOP	4	0
DS2154	A2	SEP '00	25957	0034	ATP (Anam, PI)	DK022283AAA	LQFP	4	0
DS2175	D1	OCT '00	26107	0042	ATP (Anam, PI)	DK031506AAC	SOIC	4	0
DS2181A	A2	JUL '00	25817	0016	OSEP	DE004552ABD	PLCC	4	0
DS21Q43	A3-A	JUN '00	25503	0014	ATK (Anam, K)	DN004571AAB	LQFP	4	0
DS21Q43	A3-A	SEP '00	25949	0031	Stats	DC022318AAD	LQFP	4	0
DS2502	C3	JUN '00	25567	0011	Carsem S	DM941230AG	SOIC	4	0
DS5002	C5	JUL '00	25825	0027	ATK (Anam, K)	DN012259AAL	MQFP	4	0
DS5002	C5	OCT '00	26058	0033	ATK (Anam, K)	DN022328AAJ	MQFP	4	0
DS5002	C5	JAN '01	26507	0047	ATK (Anam, K)	DN028766AAD	MQFP	4	0

RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: MIL-STD-883-2016

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1230	B1-	JUL '00	25776	0019	Fastech	117143	Module w/SMT	6	0
DS1230	B1-Y	JUL '00	25780	0020	Fastech	11387	Low Profile Module	6	0
DS1230	A1-Y	OCT '00	26095	0039	Fastech	120544	Module w/SMT	6	0
DS1230	A1-Y	JAN '01	26428	0045	Fastech	305435	Module w/SMT	6	0
DS12887	A2-	JUL '00	25806	0027	Fastech	300063	Module w/Bent Fra	6	0
DS12887	A2-	OCT '00	26070	0040	Fastech	300402	Module w/Bent Fra	6	0
DS1643	C1	AUG '00	25918	0033	Fastech	121538	Module w/Hi Densit	6	0
DS1643	C1	NOV '00	26179	0042	Fastech	122271	Module w/Hi Densit	6	0
DS1643	C1	FEB '01	26564	0104	Fastech	301297	Module w/Hi Densit	6	0

RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 60C/90% R.H.

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230	B1-	JUL '00	25779	0019	Fastech	117143	Module w/SMT	288	100	0
DS1230	B1-	JUL '00	25779	0019	Fastech	117143	Module w/SMT	960	99	0
DS1230	B1-Y	JUL '00	25783	0020	Fastech	11387	Low Profile Module	288	76	0
DS1230	A1-Y	OCT '00	26098	0039	Fastech	120544	Module w/SMT	288	100	0
DS1230	A1-Y	OCT '00	26098	0039	Fastech	120544	Module w/SMT	960	100	0
DS1230	A1-Y	JAN '01	26431	0045	Fastech	305435	Module w/SMT	288	100	0
DS1643	C1	AUG '00	25921	0033	Fastech	121538	Module w/Hi Densit	288	77	0
DS1643	C1	NOV '00	26182	0042	Fastech	122271	Module w/Hi Densit	288	77	0
DS1644	B2	& DS9034	26195	0041	Fastech	122179	Power Cap	288	77	4
DS1646	B2	JUL '00	25774	0026	Fastech	119855	Module w/Hi Densit	288	77	20
DS1646	B2	JUL '00	25774	0026	Fastech	119855	Module w/Hi Densit	576	57	7
DS1646	B2	JUL '00	25774	0026	Fastech	119855	Module w/Hi Densit	960	50	8
DS1646	B2	OCT '00	26132	0039	Fastech	122182	Module w/Hi Densit	288	77	2
DS1646	B2	JAN '01	26454	0050	Fastech	300710	Module w/Hi Densit	288	77	1
DS1991	F1	SEP '00	25939	0036	Dallas	DS922809AA-	Puk Can F50 Rev B	288	77	0
DS1991	F1	SEP '00	25939	0036	Dallas	DS922809AA-	Puk Can F50 Rev B	960	77	0
DS1992	E5	DEC '00	26345	0046	Dallas	DS028764AA	Tch Can F50	288	77	0
DS2250	E-T	JUN '00	25682	0026	Dallas	117825	SipStick w/Confor	192	11	0
DS2250	E-T	JUN '00	25682	0026	Dallas	117825	SipStick w/Confor	384	11	0
DS2250	E-T	SEP '00	25964	0035	Fastech	117888	SipStick w/Confor	192	11	0
DS2250	E-T	SEP '00	25964	0035	Fastech	117888	SipStick w/Confor	384	11	0
DS3816	A-C	& DS3801	26055	0041	Dallas	120701	BGA Module	288	33	2

RELIABILITY MONITOR

STRESS: INFANT LIFE

CONDITIONS: 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	JUL '00	25807	0027 Fastech	300063	Module w/Bent Fra	48	200	0
DS12887	A2-	OCT '00	26071	0040 Fastech	300402	Module w/Bent Fra	48	200	0

RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS21352	A4	DEC '00	26358	0044 ATP (Anam, PI)	DK031452AB	LQFP	200	71	0
DS2154	A2	SEP '00	25961	0034 ATP (Anam, PI)	DK022283AAA	LQFP	200	64	0
DS2154	A2	DEC '00	26380	0036 Stats	DC022275AAB	LQFP	200	77	0
DS21Q43	A3-A	JUN '00	25508	0014 ATK (Anam, K)	DN004571AAB	LQFP	100	38	0
DS21Q43	A3-A	SEP '00	25954	0031 Stats	DC022318AAD	LQFP	100	36	0

RELIABILITY MONITOR

STRESS: HAST

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1232	C2-L	OCT '00	26092	0039 OSEP	DE028679ADB	SOIC	100	76	0
DS1233	A5	JUL '00	25803	0025 Carsem	DM009468AA	SOT223	100	72	1
DS1233	A5	OCT '00	26129	0038 Fastech	DA017172ABA	SOT223	100	75	0
DS1233	A5	JAN '01	26446	0049 Fastech	DA033011ABA	SOT223	100	72	0
DS2181A	A2	JUL '00	25821	0016 OSEP	DE004552ABD	PLCC	100	59	0
DS2401	C2	DEC '00	26340	0035 Fastech	DM014457AD	TO92	100	77	0
DS87C520	A15	AUG '00	25869	0027 OSEP	DE013425AAD	PLCC	100	57	0
DS87C520	A15	NOV '00	26203	0042 OSEP	DE029195AAB	PLCC	100	60	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1644	B2	& DS9034	26191	0041 Fastech	122179	Power Cap	2	231	0
DS1644	B2	& DS9034	26625	0051 Fastech	300700	Low Profile Module	2	225	0
DS3816	A-C	& DS3801	26051	0041 Dallas	120701	BGA Module	2	99	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1232	C2-L	OCT '00	26087	0039	OSEP	DE028679ADB	SOIC	3	238	0
DS1232	C2-L	JAN '01	26433	0051	ATP (Anam, PI)	DK038265AAC	SOIC	3	238	0
DS1233	A5	JUL '00	25798	0025	Carsem	DM009468AA	SOT223	3	233	0
DS1233	A5	OCT '00	26124	0038	Fastech	DA017172ABA	SOT223	3	233	3
DS1233	A5	JAN '01	26441	0049	Fastech	DA033011ABA	SOT223	3	233	0
DS1267	A2	FEB '00	25173	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	3	238	0
DS1267	A1	AUG '00	25832	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	3	238	0
DS1267	A1	FEB '01	26569	0102	Carsem S	DM039441AB	TSSOP	3	238	0
DS1621	A7	MAR '00	25218	9950	OSEP	DE940040AAC	SOIC	3	241	0
DS1803	A2	NOV '99	24736	9923	ATP (Anam, PI)	DK913631AAA	SOIC	3	238	0
DS1803	A2	FEB '00	25189	0007	OSEP	DE946274AAA	SOIC	3	238	0
DS1803	A2	MAY '00	25436	0013	OSEP	DE951193AAF	SOIC	3	238	0
DS1803	A2	AUG '00	25923	0034	OSEP	DE023435AAB	SOIC	3	238	0
DS1869	A3	JUN '00	25541	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	3	241	0
DS2108	B7	MAY '00	25523	0019	ATP (Anam, PI)	DK007198AAF	SOIC	3	238	3
DS2108	B7	AUG '00	25855	0029	ATP (Anam, PI)	DK016058AA	SOIC	3	238	0
DS2108	B7	FEB '01	26577	0051	ATK (Anam, K)	DN041061AAE	SOIC	3	238	0
DS2118M	B1	SEP '00	25941	0033	ATK (Anam, K)	DN020718AAD	SSOP	3	238	0
DS2118M	B1	DEC '00	26360	0047	ATK (Anam, K)	DN033148ACE	SSOP	3	238	0
DS21352	A4	DEC '00	26353	0044	ATP (Anam, PI)	DK031452AB	LQFP	3	238	3
DS2154	A2	SEP '00	25956	0034	ATP (Anam, PI)	DK022283AAA	LQFP	3	238	0
DS2154	A2	DEC '00	26375	0036	Stats	DC022275AAB	LQFP	3	238	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2175	D1	OCT '00	26106	0042	ATP (Anam, PI)	DK031506AAC	SOIC	3	238	0
DS2175	D1	JAN '01	26420	0046	ATP (Anam, PI)	DE033119AAB	SOIC	3	238	0
DS21Q43	A3-A	JUN '00	25502	0014	ATK (Anam, K)	DN004571AAB	LQFP	3	239	0
DS21Q43	A3-A	SEP '00	25948	0031	Stats	DC022318AAD	LQFP	3	239	0
DS21Q43	A3-A	DEC '00	26367	0034	ATK (Anam, K)	DN027568AAC	LQFP	3	239	0
DS2502	C3	JUN '00	25566	0011	Carsem S	DM941230AG	SOIC	3	238	0
DS2502	C3	JUL '00	25811	0017	CPS (ChipPac, China)	DH948636AG	TSOC	3	151	0
DS80CH11	A4	DEC '00	26396	0033	ATK (Anam, K)	DN022359AAA	LQFP	3	239	0

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1000	E3	OCT '00	26049	0033	OSEP	DE009456ACE	SOIC	274	77	0
DS1000	E3	OCT '00	26049	0033	OSEP	DE009456ACE	SOIC	959	77	0
DS1267	A2	FEB '00	25178	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	274	77	0
DS1267	A2	FEB '00	25178	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	959	77	0
DS1267	A1	AUG '00	25837	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	274	75	0
DS1267	A1	AUG '00	25837	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	959	69	0
DS12887	A2-	JUL '00	25809	0027	Fastech	300063	Module w/Bent Fra	274	100	0
DS12887	A2-	JUL '00	25809	0027	Fastech	300063	Module w/Bent Fra	959	100	0
DS12887	A2-	OCT '00	26073	0040	Fastech	300402	Module w/Bent Fra	274	82	0
DS12887	A2-	OCT '00	26073	0040	Fastech	300402	Module w/Bent Fra	959	82	0
DS1302	A3	DEC '00	26335	0032	CPS (ChipPac, China)	DH028629AB	PDIP	274	77	0
DS1302	A3	AUG '00	25934	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	274	77	0
DS1302	A3	AUG '00	25934	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	959	77	0
DS1621	A7	MAR '00	25223	9950	OSEP	DE940040AAC	SOIC	274	70	0
DS1621	A7	MAR '00	25223	9950	OSEP	DE940040AAC	SOIC	959	69	0
DS1803	A2	NOV '99	24741	9923	ATP (Anam, PI)	DK913631AAA	SOIC	274	67	0
DS1803	A2	NOV '99	24741	9923	ATP (Anam, PI)	DK913631AAA	SOIC	959	67	0
DS1803	A2	FEB '00	25194	0007	OSEP	DE946274AAA	SOIC	274	68	0
DS1803	A2	FEB '00	25194	0007	OSEP	DE946274AAA	SOIC	959	57	0
DS1803	A2	MAY '00	25441	0013	OSEP	DE951193AAF	SOIC	274	64	0
DS1803	A2	AUG '00	25928	0034	OSEP	DE023435AAB	SOIC	274	64	0
DS1869	A3	JUN '00	25546	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	274	70	1

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2108	B7	MAY '00	25528	0019	ATP (Anam, PI)	DK007198AAF	SOIC	274	77	0
DS2108	B7	MAY '00	25528	0019	ATP (Anam, PI)	DK007198AAF	SOIC	959	76	0
DS2108	B7	AUG '00	25860	0029	ATP (Anam, PI)	DK016058AA	SOIC	274	77	3
DS2108	B7	AUG '00	25860	0029	ATP (Anam, PI)	DK016058AA	SOIC	959	74	0
DS2175	D1	OCT '00	26111	0042	ATP (Anam, PI)	DK031506AAC	SOIC	274	77	0
DS2175	D1	OCT '00	26111	0042	ATP (Anam, PI)	DK031506AAC	SOIC	959	77	0
DS21Q43	A3-A	JUN '00	25507	0014	ATK (Anam, K)	DN004571AAB	LQFP	274	39	0
DS21Q43	A3-A	JUN '00	25507	0014	ATK (Anam, K)	DN004571AAB	LQFP	959	36	0
DS21Q43	A3-A	SEP '00	25953	0031	Stats	DC022318AAD	LQFP	274	46	0
DS2502	C3	JUN '00	25571	0011	Carsem S	DM941230AG	SOIC	274	77	0
DS2502	C3	JUN '00	25571	0011	Carsem S	DM941230AG	SOIC	959	76	0
DS5002	C5	JUL '00	25829	0027	ATK (Anam, K)	DN012259AAL	MQFP	274	42	0
DS5002	C5	OCT '00	26062	0033	ATK (Anam, K)	DN022328AAJ	MQFP	274	42	0
DS80C320	C5	OCT '00	26067	0038	CPS (ChipPac, China)	DH026369ABA	PDIP	274	77	0
DS80C320	C5	OCT '00	26067	0038	CPS (ChipPac, China)	DH026369ABA	PDIP	959	77	0
DS80C320	C5	JAN '01	26458	0049	CPS (ChipPac, China)	DH031585BAA	PDIP	274	77	0

RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1000	E3	OCT '00	26050	0033	OSEP	DE009456ACE	SOIC	96	38	0
DS1232	C2-L	OCT '00	26093	0039	OSEP	DE028679ADB	SOIC	96	39	0
DS1233	A5	JUL '00	25804	0025	Carsem	DM009468AA	SOT223	96	37	0
DS1233	A5	OCT '00	26130	0038	Fastech	DA017172ABA	SOT223	96	40	0
DS1233	A5	JAN '01	26447	0049	Fastech	DA033011ABA	SOT223	96	40	0
DS1267	A2	FEB '00	25179	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	96	36	0
DS1267	A1	AUG '00	25838	0021	ATP (Anam, PI)	DK012170AAA	TSSOP	96	35	0
DS1302	A3	AUG '00	25935	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	96	38	0
DS1302	A3	DEC '00	26336	0032	CPS (ChipPac, China)	DH028629AB	PDIP	96	38	0
DS1803	A2	NOV '99	24742	9923	ATP (Anam, PI)	DK913631AAA	SOIC	96	40	0
DS1803	A2	FEB '00	25195	0007	OSEP	DE946274AAA	SOIC	96	35	0
DS1803	A2	MAY '00	25442	0013	OSEP	DE951193AAF	SOIC	96	35	0
DS1803	A2	AUG '00	25929	0034	OSEP	DE023435AAB	SOIC	96	30	0
DS2108	B7	MAY '00	25529	0019	ATP (Anam, PI)	DK007198AAF	SOIC	96	37	0
DS2108	B7	AUG '00	25861	0029	ATP (Anam, PI)	DK016058AA	SOIC	96	33	0
DS2118M	B1	SEP '00	25946	0033	ATK (Anam, K)	DN020718AAD	SSOP	96	77	0
DS2118M	B1	DEC '00	26365	0047	ATK (Anam, K)	DN033148ACE	SSOP	96	77	0
DS2175	D1	OCT '00	26112	0042	ATP (Anam, PI)	DK031506AAC	SOIC	96	40	0
DS2181A	A2	JUL '00	25822	0016	OSEP	DE004552ABD	PLCC	96	38	0
DS2401	C2	DEC '00	26341	0035	Fastech	DM014457AD	TO92	96	40	0
DS2502	C3	JUL '00	25814	0017	CPS (ChipPac, China)	DH948636AG	TSOC	96	70	0
DS5002	C5	JUL '00	25830	0027	ATK (Anam, K)	DN012259AAL	MQFP	96	37	0

RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS5002	C5	OCT '00	26063	0033 ATK (Anam, K)	DN022328AAJ	MQFP	96	37	0
DS80C320	C5	OCT '00	26068	0038 CPS (ChipPac, China)	DH026369ABA	PDIP	96	37	0
DS80C320	C5	JAN '01	26459	0049 CPS (ChipPac, China)	DH031585BAA	PDIP	96	38	0